

FOR IMMEDIATE RELEASE

BEST Inc. Presents StencilQuik™ for Simplifying BGA Rework Challenges

StencilQuik™ eliminates time spent repairing solder mask damage during BGA rework.

Rolling Meadows, Illinois (April 1, 2025) – BEST Inc., a leader in electronic component rework services, training, and rework tools is thrilled to announce StencilQuik™ rework stencils. This innovative product is specifically designed for placing Ball Grid Arrays (BGAs) or Chip Scale Packages (CSPs) during the rework process.

StencilQuik™ is custom-made to match the exact specifications of your components to ensure perfect alignment during rework. The stencil remains securely in place throughout the rework process, becoming an integral part of the PCB assembly. Manufactured from polyimide film with a high-temperature adhesive, this material resembles what is commonly used for bar code labels and for protecting gold fingers during wave soldering. StencilQuik™ is ESD-safe and has a residue-free adhesive backing that ensures a clean application.

An added benefit from this unique product is the ability to overcome solder mask damage which can occur during component removal. StencilQuik™ was designed to be placed over these damaged areas without the need for repair and still result in a successful component placement.

The StencilQuik™ rework process involves a few simple steps starting with preparing the rework site by removing any residual solder or flux residue following BGA removal. Next, remove the adhesive backed stencil and place it on the rework site by aligning the apertures with the corresponding pads. Once properly aligned, use a squeegee to fill each aperture completely with solder paste. After cleaning the residual paste off the stencil, place the component on top of StencilQuik™ and reflow for final placement.

As part of the IPC 7711 BGA rework processes, StencilQuik™ rework stencils have undergone extensive reliability testing confirming their dependability. Furthermore, third-party studies have validated that the surface insulation resistance (SIR) characteristics of BGAs placed using StencilQuik™ stencils, meet the acceptable standards for SIR values on PCB assemblies.

About BEST Inc.

BEST Inc. is an ISO 9001:2015 and ITAR certified provider of PCB and component rework services and products along with being a certified IPC Training Center. Our commitment is to provide the highest quality services and products with outstanding customer service to serve our customers' needs.

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